

SOT2021-1

BGA548, ball grid array package, 548 terminals, 0.5 mm pitch,
15 mm x 15 mm x 1.94 mm body

16 May 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA548
Package style descriptive code	BGA (ball grid array)
Mounting method type	S (surface mount)
Issue date	09-05-2019
Manufacturer package code	98ASA01401D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	15	-	mm
package width	-	15	-	mm
package height	-	1.94	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	548	-	



2 Package outline

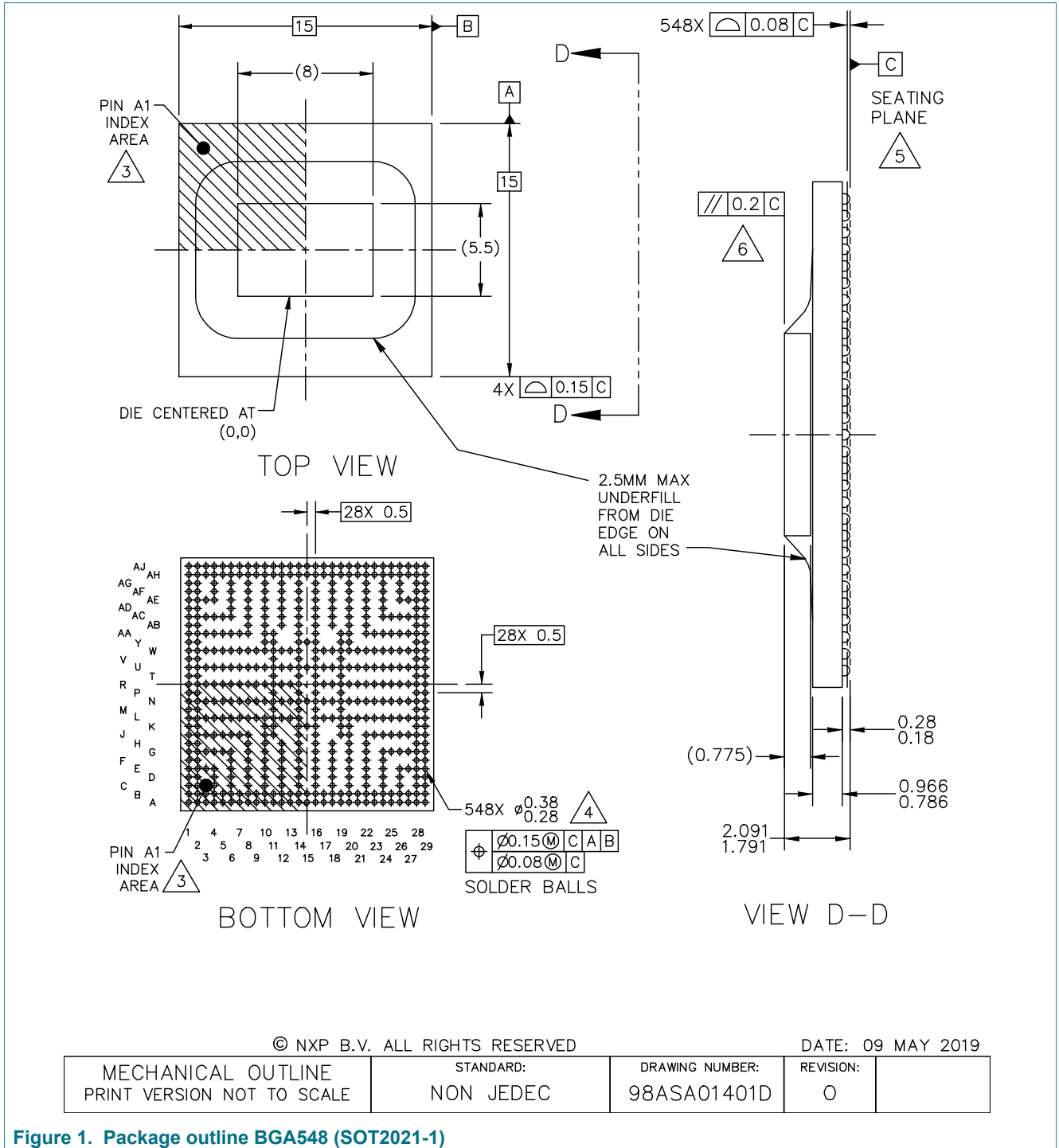
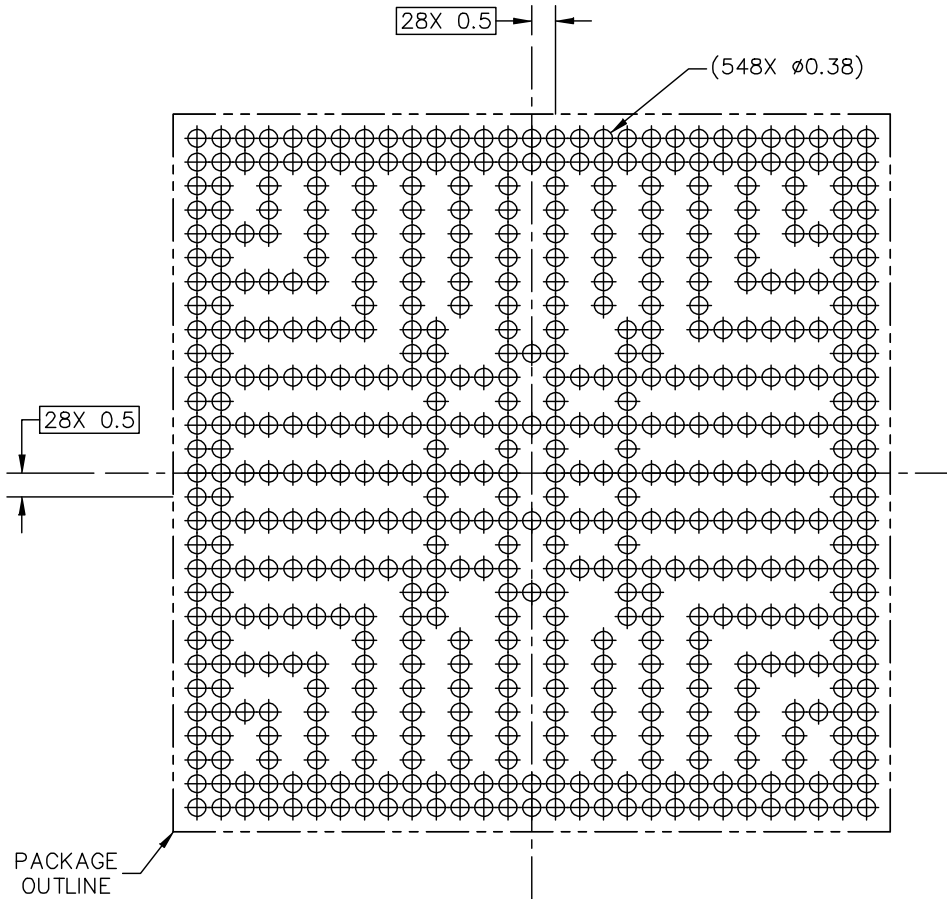


Figure 1. Package outline BGA548 (SOT2021-1)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

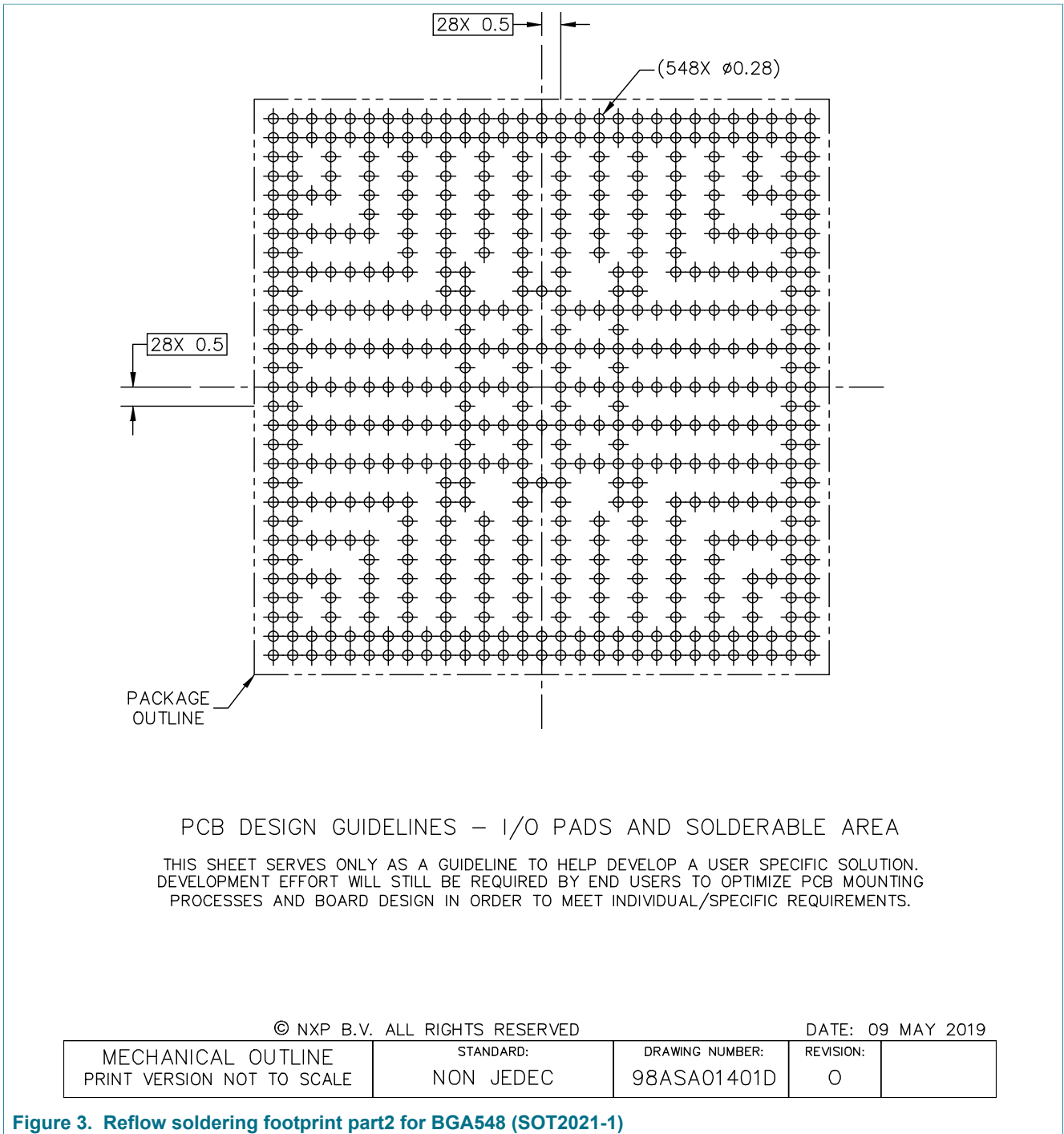
THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 2. Reflow soldering footprint part1 for BGA548 (SOT2021-1)



BGA548, ball grid array package, 548 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.94 mm body

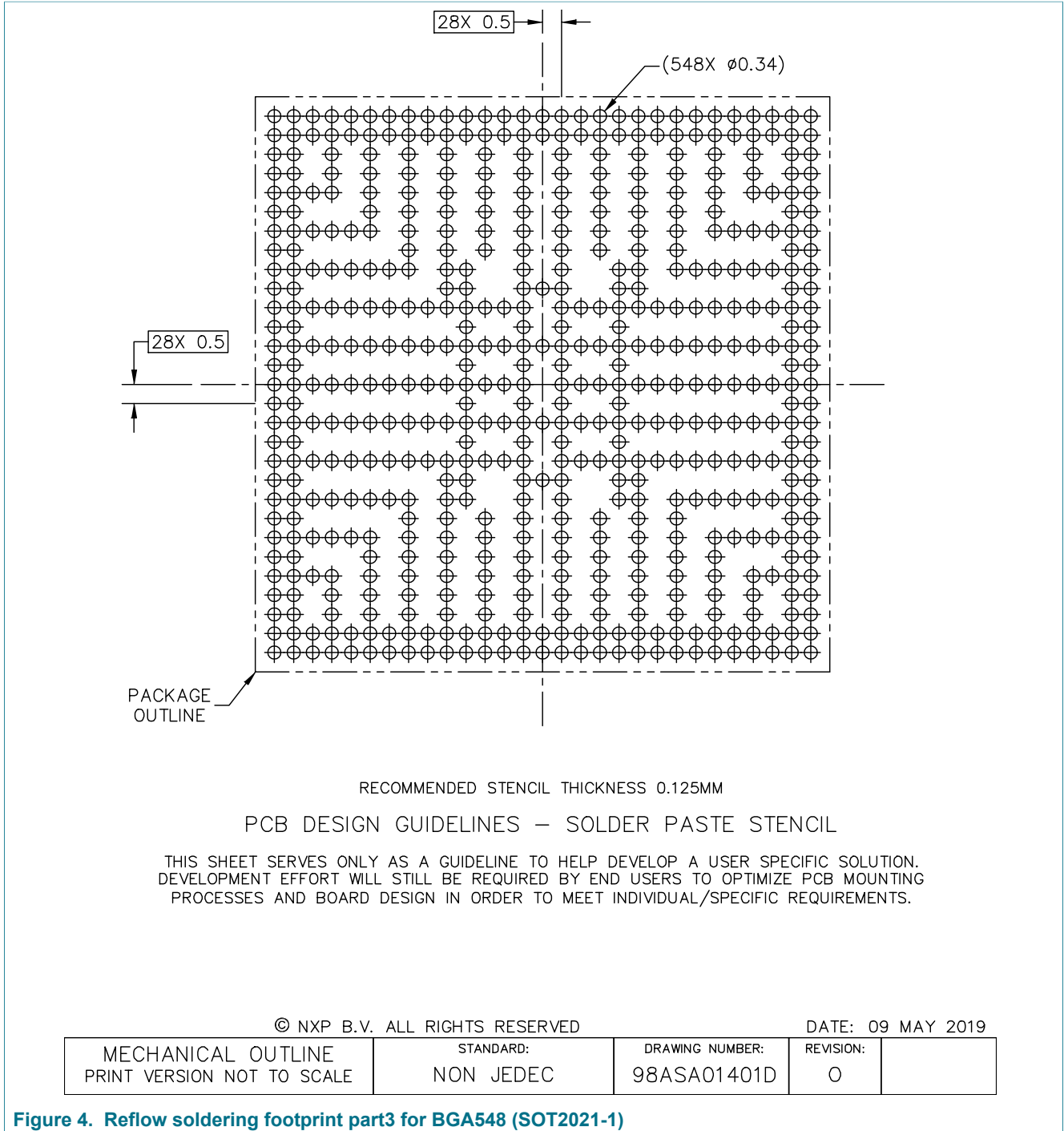


Figure 4. Reflow soldering footprint part3 for BGA548 (SOT2021-1)

BGA548, ball grid array package, 548 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.94 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note BGA548 (SOT2021-1)

4 Legal information

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